

Low Density Polyethylene SPB608

Description:

SPB608 is a low density polyethylene designed for injection molding. This grade shows excellent processability being indicated for applications where low viscosity is required during processing. Injection molded products with this resin shows good flexibility. Additives free. The minimum biobased content of this grade is 95%, determined according to ASTM D6866.

Applications:

Masterbatches. Covers and injected parts with large flat area.

Control Properties:

	ASTM Method	Units	Values
Melt Flow Rate (190/2.16)	D 1238	g/10 min	30
Density	D 1505	g/cm ³	0.915

Properties:

Plaque Properties^a

	ASTM Method	Units	Values
Tensile Strength at Break	D 638	MPa	8
Tensile Elongation at Break	D 638	%	390
Tensile Strength at Yield	D 638	MPa	8
Flexural Modulus – 1% Secant	D 790	MPa	450
Shore D Hardness	D 2240	-	39
Vicat Softening Temperature at 10 N	D 1525	°C	79

(a) Test specimens prepared from compression molded sheet made according to ASTM D 4703.

Recommended Processig Conditions:

Injection Molding

- Temperature profile.....from.180 to 210°C
- Mold temperature.....5 to 25°C

Final Remarks:

1. This resin meets the requirements for olefin polymers as defined in 21 CFR, section 177.1520 issued by FDA – Food and Drug Administration in force on the date of publication of this specification. The additives present are covered in appropriate regulation by FDA
2. The information presented in this Data Sheet reflects typical values obtained in our laboratories, but should not be considered as absolute or as warranted values. Only the properties and values mentioned on the Certificate of Quality are considered as guarantee of the product.
3. In some applications, Braskem has developed tailor-made resins to reach specific requirements.
4. In case of doubt regarding utilization, or for other applications, please contact our Technical Assistance.
5. For information about safety, handling, individual protection, first aids and waste disposal, please see MSDS. CAS Registry number: 009002-88-4.
6. The mentioned values in this report can be changed at any moment without Braskem previous communication.
7. Unless specifically indicated, the Company does not recommend this grade for packages, parts or any other product intended for medical/pharmaceutical use
8. This resin does not contain the substance Bisphenol A (BPA, CAS # No. 80-05-7) in its composition.